ABSTRACT

The present invention aims at, in forming packages (products) 5 by cutting a molded substrate 1, obtaining high-quality and reliable products 5 and enhancing the productivity of the products 5. First, individual packages 5(1c) fastened by a first package fastening mechanism 11 are transferred onto the package placing side (upper side) 12a of an invertible attachment plate 12. Then the invertible attachment plate 12 is inverted so that the package placing side 12a will be the lower side, and the packages 5(1c) are examined from below by a first examination mechanism 13. Next, the first-examined packages 5(1c) held on the invertible attachment plate 12 are passed and transferred onto the package placing side 14a of a placing plate 14, and the first-examined packages 5(1c) are examined from above by a second examination mechanism 15. After that, the second-examined packages 5(1c) are transferred to a placing table 17 at a package placing position 18a by a second package fastening mechanism 16.